EM484M3244VTA

128Mb (1M×4Bank×32) Synchronous DRAM

Features

- Fully Synchronous to Positive Clock Edge
- Single 3.3V ±0.3V Power Supply
- LVTTL Compatible with Multiplexed Address
- Programmable Burst Length (B/L) 1, 2, 4, 8 or Full Page
- Programmable CAS Latency (C/L) 2 or 3
- Data Mask (DQM) for Read / Write Masking
- Programmable Wrap Sequence
- Sequential (B/L = 1/2/4/8/full Page)
- Interleave (B/L = 1/2/4/8)
- Burst Read with Single-bit Write Operation
- All Inputs are Sampled at the Rising Edge of the System Clock
- Auto Refresh and Self Refresh

Ordering Information

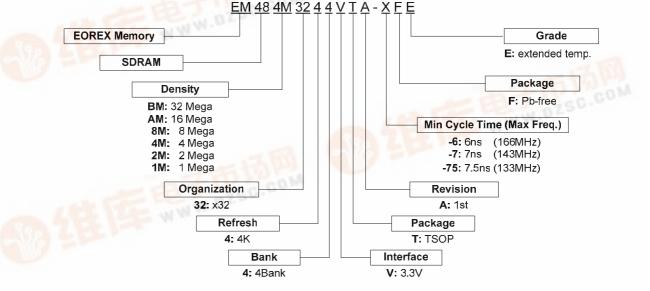
4,096 Refresh Cycles / 64ms (15.625us)

Description

The EM484M3244VTA is Synchronous Dynamic Random Access Memory (SDRAM) organized as 1Meg words x 4 banks by 32 bits. All inputs and outputs are synchronized with the positive edge of the clock.

The 128Mb SDRAM uses synchronized pipelined architecture to achieve high speed data transfer rates and is designed to operate at 3.3V low power memory system. It also provides auto refresh with power saving / down mode. All inputs and outputs voltage levels are compatible with LVTTL. Available packages:TSOPII 86P 400mil.

Part No	Organization	Max. Freq	Package	Grade	Pb
EM484M3244VTA-75F	4M X 32	133MHz @CL3	86pin TSOP(II)	Commercial	Free
EM484M3244VTA-7F	4M X 32	143MHz @CL3	86pin TSOP(II)	Commercial	Free
EM484M3244VTA-6F	4M X 32	166 <mark>MH</mark> z @CL3	86pin TSOP(II)	Commercial	Free

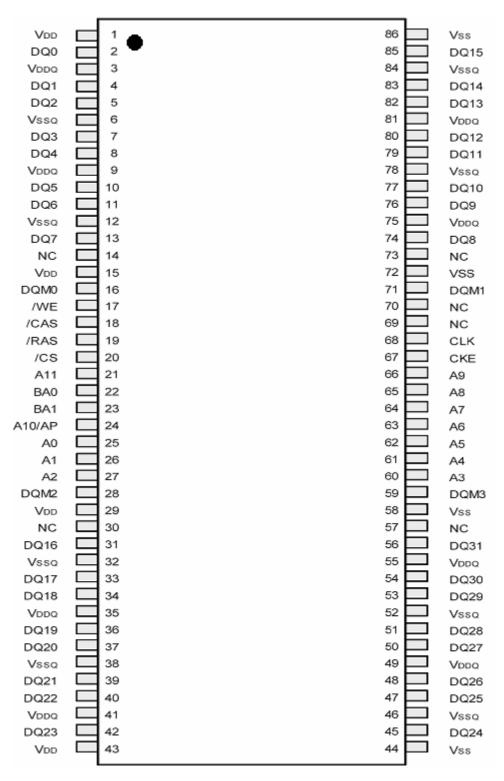




* EOREX reserves the right to change products or specification without notice.

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Pin Assignment



86pin TSOP-II / (400mil × 875mil) / (0.5mm Pin pitch)

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Pin Description (Simplified)

Pin	Name	Function
68	CLK	(System Clock) Master clock input (Active on the positive rising edge)
20	/CS	(Chip Select) Selects chip when active
67	CKE	(Clock Enable) Activates the CLK when "H" and deactivates when "L". CKE should be enabled at least one cycle prior to new command. Disable input buffers for power down in standby.
21,24~27,60~66	A0~A11	 (Address) Row address (A0 to A11) is determined by A0 to A11 level at the bank active command cycle CLK rising edge. CA (CA0 to CA7) is determined by A0 to A7 level at the read or write command cycle CLK rising edge. And this column address becomes burst access start address. A10 defines the pre-charge mode. When A10= High at the pre-charge command cycle, all banks are pre-charged. But when A10= Low at the pre-charge command cycle, only the bank that is selected by BA0/BA1 is pre-charged.
22, 23	BA0, BA1	(Bank Address) Selects which bank is to be active.
19	/RAS	(Row Address Strobe) Latches Row Addresses on the positive rising edge of the CLK with /RAS "L". Enables row access & pre-charge.
18	/CAS	(Column Address Strobe) Latches Column Addresses on the positive rising edge of the CLK with /CAS low. Enables column access.
17	/WE	(Write Enable) Latches Column Addresses on the positive rising edge of the CLK with /CAS low. Enables column access.
16,28,59,71	DQM0~DQM3	(Data Input/Output Mask) DQM controls I/O buffers.
2, 4, 5, 7, 8, 10, 11,13,31,33,34,36 ,37,39,40,42,45, 47,48,50,51,53, 54,56,74,76,77, 79,80,82,83,85	DQ0~DQ31	(Data Input/Output) DQ pins have the same function as I/O pins on a conventional DRAM.
1,15,29,43/ 44,58,72,86	V_{DD}/V_{SS}	(Power Supply/Ground) V_{DD} and V_{SS} are power supply pins for internal circuits.
3,9,35,41,49,55, 75,81/6,12,32,38, 46,52,78,84	V_{DDQ}/V_{SSQ}	(Power Supply/Ground) V_{DDQ} and V_{SSQ} are power supply pins for the output buffers.
14,30,57,69,70, 73	NC	(No Connection) This pin is recommended to be left No Connection on the device.

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Symbol	Item	Rating	Units
V _{IN} , V _{OUT}	Input, Output Voltage	-0.3 ~ +4.6	V
V_{DD}, V_{DDG}	Power Supply Voltage	-0.3 ~ +4.6	V
T _{OP}	Operating Temperature Range	Commercial 0 ~ +70	°C
I OP	Operating temperature trange	Extended -25 ~ +85	C
T _{STG}	Storage Temperature Range	-55 ~ +150	°C
PD	Power Dissipation	1	W
l _{os}	Short Circuit Current	50	mA

Absolute Maximum Rating

Note: Caution Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Capacitance (V_{CC}=3.3V, f=1MHz, T_A=25°C)

Symbol	Parameter	Min.	Тур.	Max.	Units
C _{CLK}	Clock Capacitance	2.5		4.0	pF
Cı	Input Capacitance for CLK, CKE, Address, /CS, /RAS, /CAS, /WE, DQML, DQMU	2.5		4.5	pF
Co	Input/Output Capacitance	4.0		6.5	рF

Recommended DC Operating Conditions ($T_A=0^{\circ}C \sim 70^{\circ}C$)

Symbol	Parameter	Min.	Тур.	Max.	Units
V _{DD}	Power Supply Voltage	3.0	3.3	3.6	V
V _{DDQ}	Power Supply Voltage (for I/O Buffer)	3.0	3.3	3.6	V
V _{IH}	Input Logic High Voltage	2.0		V _{DD} +0.3	V
V _{IL}	Input Logic Low Voltage	-0.3		0.8	V

Note: * All voltages referred to V_{SS}.

* V_{IH} (max.) = 5.6V for pulse width 3ns

* V_{IL} (min.) = -2.0V for pulse width 3ns

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Recommended DC Operating Conditions

(V _{DD} =3.3V±0.3V, T _A =0°C ~70°C	
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)

Symbol	Parameter	Test Conditions	Max.	Units
I _{CC1}	Operating Current (Note 1)	Burst length=1, t _{RC} ≥t _{RC} (min.), I _{OL} =0mA, One bank active	100	mA
I _{CC2P}	Precharge Standby Current in	CKE≤V _{IL} (max.), t _{CK} =15ns	1	mA
I _{CC2PS}	Power Down Mode	CKE≤V _{IL} (max.), t _{CK} =∞	1	mA
I _{CC2N}	Precharge Standby Current in Non-power Down Mode	CKE≥V _{IL} (min.), t _{CK} =15ns, /CS≥V _{IH} (min.) Input signals are changed one time during 30ns	35	mA
I _{CC2NS}		CKE≥V _{IL} (min.), t _{CK} =∞ , Input signals are stable	10	mA
I _{CC3P}	Active Standby Current in	CKE≤V _{IL} (max.), t _{CK} =15ns	5	mA
I _{CC3PS}	Power Down Mode	CKE≤V _{IL} (max.), t _{CK} =∞	1	mA
I _{CC3N}	Active Standby Current in Non-power Down Mode	CKE≥V _{IL} (min.), t _{CK} =15ns, /CS≥V _{IH} (min.) Input signals are changed one time during 30ns	60	mA
I _{CC3NS}		CKE≥V _{IL} (min.), t _{CK} =∞ , Input signals are stable	30	mA
I _{CC4}	Operating Current (Burst Mode) ^(Note 2)	t _{CCD} ≥2CLKs, I _{OL} =0mA	160	mA
I _{CC5}	Refresh Current (Note 3)	t _{RC} ≥t _{RC} (min.)	120	mA
I _{CC6}	Self Refresh Current	CKE≤0.2V	1 (Note 4)	mA

*All voltages referenced to V_{SS} .

Note 1: I_{CC1} depends on output loading and cycle rates.

Specified values are obtained with the output open.

Input signals are changed only one time during t_{CK} (min.)

- **Note 2:** I_{CC4} depends on output loading and cycle rates. Specified values are obtained with the output open. Input signals are changed only one time during t_{CK} (min.)
- *Note 3:* Input signals are changed only one time during t_{CK} (min.)

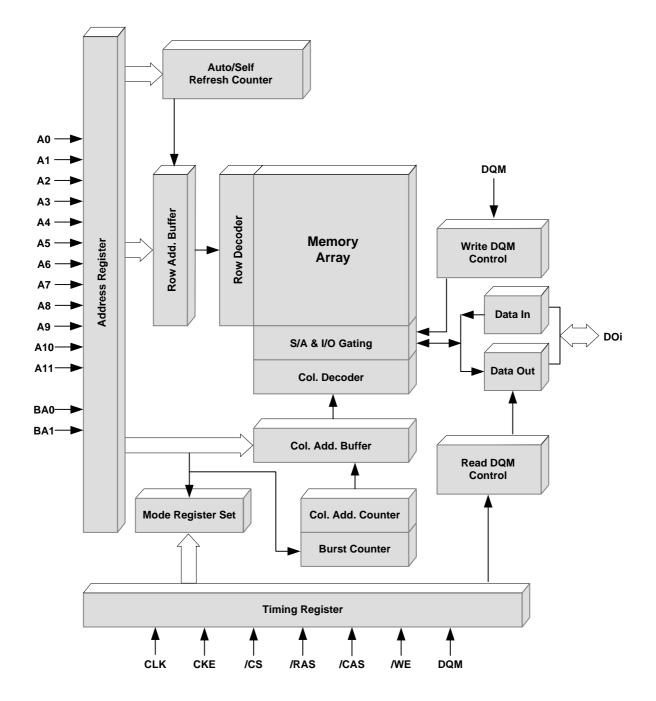
Note 4: Standard power version.

Recommended DC Operating Conditions (Continued)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
IIL	Input Leakage Current	$0 \le V_I \le V_{DDQ}, V_{DDQ} = V_{DD}$ All other pins not under test=0V	-0.5		+0.5	uA
I _{OL}	Output Leakage Current	$0 \le V_O \le V_{DDQ}$, D_{OUT} is disabled	-0.5		+0.5	uA
V _{OH}	High Level Output Voltage	I _O =-4mA	2.4			V
V _{OL}	Low Level Output Voltage	I _O =+4mA			0.4	V

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Block Diagram

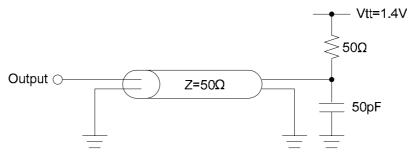


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AC Operating Test Conditions

(V_{DD}=3.3V±0.3V, T_A=0°C ~70°C)

Item	Conditions
Output Reference Level	1.4V/1.4V
Output Load	See diagram as below
Input Signal Level	2.4V/0.4V
Transition Time of Input Signals	2ns
Input Reference Level	1.4V



AC Operating Test Characteristics

(V_{DD}=3.3V±0.3V, T_A=0°C ~70°C)

Symbol	Parameter		-	6	-	7	-7	.5	Units
Symbol	Falameter		Min.	Max.	Min.	Max.	Min.	Max.	Units
+	Clock Cycle Time	CL=3	6		7		7.5		ns
t _{ск}		CL=2	10		10		10		115
+	Access Time form CLK	CL=3		5.5		5.5		6	20
t _{AC}	AC Access Time form CLK	CL=2		5		6		6	ns
t _{CH}	CLK High Level Width		2		2		2		ns
t _{CL}	CLK Low Level Width		2		2		2		ns
4	Data-out Hold Time	CL=3	2		2		2		20
t _{он}	Data-out Hold Time	CL=2							ns
4	Data-out High Impedance	CL=3		6		7		7	20
t _{HZ}	Time (Note 5)	CL=2							ns
t _{LZ}	Data-out Low Impedance Time		0		0		0		ns
t _{IH}	Input Hold Time		1		1		1		ns
t _{IS}	Input Setup Time		1.5		2		2		ns

* All voltages referenced to V_{SS} .

Note 5: t_{HZ} defines the time at which the output achieve the open circuit condition and is not referenced to output voltage levels.

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AC Operating Test Characteristics (Continued)

Symbol	Parameter		-	6	-	7	-7	75	Units
Symbol	Falameter		Min.	Max.	Min.	Max.	Min.	Max.	Units
t _{RC}	ACTIVE to ACTIVE Comman Period (Note 6)	nd	60		65		67		ns
t _{RAS}	ACTIVE to PRECHARGE Command Period ^(Note 6)		42	100k	45	100k	45	100k	ns
t _{RP}	PRECHARGE to ACTIVE Command Period ^(Note 6)		18		18		18		ns
t _{RCD}	ACTIVE to READ/WRITE Delay Time ^(Note 6)		18		18		18		ns
t _{RRD}	ACTIVE(one) to ACTIVE(another) Command ^(Note 6)		12		14		16		ns
t _{CCD}	READ/WRITE Command to READ/WRITE Command		1		1		1		CLK
t _{DPL}	Date-in to PRECHARGE Command		2		2		2		CLK
t _{BDL}	Date-in to BURST Stop Command		1		1		1		CLK
	Data-out to High	CL=3	3		3		3		
τ _{ROH}	t _{ROH} Impedance from PRECHARGE Command		2		2		2		CLK
t _{REF}	Refresh Time (4,096 cycle)			64		64		64	ms

(V_{DD}=3.3V±0.3V, T_A=0°C ~70°C)

* All voltages referenced to V_{SS} .

Note 6: These parameters account for the number of clock cycles and depend on the operating frequency of the clock, as follows:

The number of clock cycles = Specified value of timing/clock period (Count Fractions as a whole number)

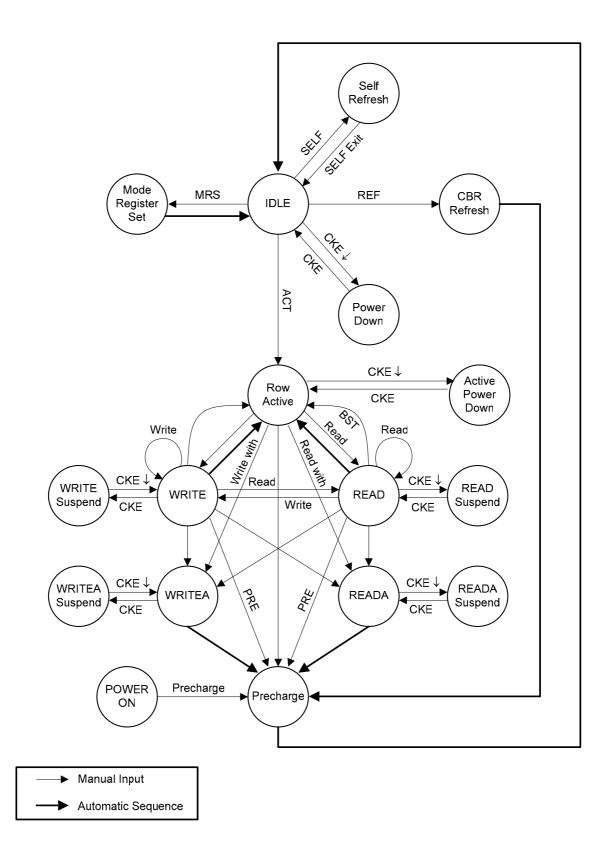
Recommended Power On and Initialization

The following power on and initialization sequence guarantees the device is preconditioned to each user's specific needs. (Like a conventional DRAM) During power on, all V_{DD} and V_{DDQ} pins must be built up simultaneously to the specified voltage when the input signals are held in the "NOP" state. The power on voltage must not exceed V_{DD} +0.3V on any of the input pins or V_{DD} supplies. (CLK signal started at same time)

After power on, an initial pause of 200 μ s is required followed by a precharge of all banks using the precharge command.

To prevent data contention on the DQ bus during power on, it is required that the DQM and CKE pins be held high during the initial pause period. Once all banks have been precharged, the Mode Register Set Command must be issued to initialize the Mode Register. A minimum of eight Auto Refresh cycles (CBR) are also required, and these may be done before or after programming the Mode Register.

Simplified State Diagram



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BA1	BAO	A11	A10	A9	A8	A7	A6	A	5 A4	A3	A2	A	1	۹0
		Ор	eration N	Node		CAS Latency BT Burst Leng					ength	ngth		
L														
										Burst	t Lengt	h		
								S	equentia	I Inter	leave	A2	A1	A0
									1		1	0	0	0
									2		2	0	0	1
									4		4	0	1	0
									8		3	0	1	1
									Reserved		erved	1	0	0
									Reserved Reserved		erved	1	0	1
									ⁱ ull Page		erved erved	1 1	1	0
									ull Fage	Rese	erveu	I	I	I
					Dem		1			4.0	/			
						rst Type				A3				
						erleave quential				1 0				
					360	quentiai				0				
							$\mathbf{+}$							
				CAS	S Latency	/	A6		A5	A4				
				Re	eserved		0		0	0				
				Re	eserved		0		0	1				
					2		0		1	0				
					3		0		1	1				
					eserved		1		0	0				
				-	eserved		1	_	0	1				
					eserved		1		1	0				
				Re	eserved		1		1	1				
	-													
	BA1	BA0	A11	A10	A9	A8	A7	,		Opera	tion Mo	ode		
	0	0	0	0	0	0	0		Normal					
	0	0	0	0	1	0	0		Burst F	Read wit		le-bi	Write	e

Address Input for Mode Register Set

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Burst Type (A3)

Burst Length	A2	A1	A0	Sequential Addressing	Interleave Addressing
2	Х	Х	0	0 1	0 1
2	Х	Х	0	10	10
	Х	0	0	0123	0123
4	Х	0	1	1230	1032
4	Х	1	0	2301	2301
	Х	1	1	3012	3210
	0	0	0	0 1 2 3 4 5 6 7	0 1 2 3 4 5 6 7
	0	0	1	12345670	10325476
	0	1	0	23456701	23016745
8	0	1	1	34567012	32107654
0	1	0	0	45670123	45670123
	1	0	1	56701234	54761032
	1	1	0	67012345	67452301
	1	1	1	70123456	76543210
Full Page*	n	n	n	Cn Cn+1 Cn+2	-

* Page length is a function of I/O organization and column addressing \times 32 (CA0 ~ CA7): Full page = 256bits

1. Command Truth Table

Command	Symbol	CK	E	/CS	/RAS	/CAS	/WE	BA0,	A10	A11,
Command	Symbol	n-1	n	/00		7043	/ / / L	BA1	AIU	A9~A10
Ignore Command	DESL	Н	Х	Н	Х	Х	Х	Х	Х	Х
No Operation	NOP	H	Х	L	H	Н	н	Х	Х	Х
Burst Stop	BSTH	Н	Х	L	Н	Н	L	Х	Х	Х
Read	READ	Н	Х	L	Н	L	Н	V	L	V
Read with Auto Pre-charge	READA	Н	Х	L	Н	L	Н	V	Н	V
Write	WRIT	Н	Х	L	Н	L	L	V	L	V
Write with Auto Pre-charge	WRITA	Н	Х	L	L	Н	Н	V	Н	V
Bank Activate	ACT	Н	Х	L	L	Н	Н	V	V	V
Pre-charge Select Bank	PRE	Н	Х	L	L	Н	L	V	L	Х
Pre-charge All Banks	PALL	Н	Х	L	L	Н	L	Х	Н	Х
Mode Register Set	MRS	Н	Х	L	L	L	L	L	L	V

H = High level, L = Low level, X = High or Low level (Don't care), V = Valid data input

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2. DQM Truth Table

Command	Symbol	Cł	<e< th=""><th colspan="2">/CS</th></e<>	/CS	
Command	Symbol	n-1	n	/03	
Data Write/Output Enable	ENB	Н	Х	Н	
Data Mask/Output Disable	MASK	Н	Х	L	
Upper Byte Write Enable/Output Enable	BSTH	Н	Х	L	
Read	READ	Н	Х	L	
Read with Auto Pre-charge	READA	Н	Х	L	
Write	WRIT	Н	Х	L	
Write with Auto Pre-charge	WRITA	Н	Х	L	
Bank Activate	ACT	Н	Х	L	
Pre-charge Select Bank	PRE	Н	Х	L	
Pre-charge All Banks	PALL	Н	Х	L	
Mode Register Set	MRS	Н	Х	L	

H = High level, L = Low level, X = High or Low level (Don't care), V = Valid data input

3. CKE Truth Table

ltem	Command	Symbol	CKE		/CS	/RAS	/CAS	/WE	Addr.	
nem	Command	Symbol	n-1	n	/03	/NAS	/CA3		Auui.	
Activating	Clock Suspend Mode Entry		Н	L	Х	Х	Х	Х	Х	
Any	Clock Suspend Mode		L	L	Х	Х	Х	Х	Х	
Clock Suspend	Clock Suspend Mode Exit		L	н	х	Х	Х	Х	х	
Idle	CBR Refresh Command	REF	Н	Н	L	L	L	Н	Х	
Idle	Self Refresh Entry	SELF	Н	L	L	L	L	Н	Х	
Self Refresh	Self Refresh Exit		L	Н	L	Н	Н	Н	Х	
Sell Kellesh			L	Н	Н	Х	Х	Х	Х	
Idle	Power Down Entry		Н	L	Х	Х	Х	Х	Х	
Power Down	Power Down Exit		L	Н	Х	Х	Х	Х	Х	

Remark H = High level, L = Low level, X = High or Low level (Don't care)

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Current	/CS	/R	/C	/W	Addr.	Command	Action
State							
	Н	Х	Х	Х	Х	DESL	Nop or power down (Note 8)
	L	Н	Н	Х	Х	NOP or BST	Nop or power down (Note 8)
	L	н	L	Н	BA/CA/A10	READ/READA	ILLEGAL (Note 9)
	L	Н	L	L	BA/CA/A10	WRIT/WRITA	ILLEGAL ^(Note 9)
Idle	L	L	Н	Н	BA/RA	ACT	Row activating
	L	L	Н	L	BA, A10	PRE/PALL	Nop
	L	L	L	н	Х	REF/SELF	Refresh or self refresh (Note 10)
	L	L	L	L	Op-Code	MRS	Mode register accessing
	Н	Х	Х	Х	Х	DESL	Nop
	L	Н	Н	Х	Х	NOP or BST	Nop (Note 11)
	L	Н	L	Н	BA/CA/A10	READ/READA	Begin read: Determine AP (Note 11)
Row	L	Н	L	L	BA/CA/A10	WRIT/WRITA	Begin write: Determine AP (Note 11)
Active	L	L	Н	н	BA/RA	ACT	ILLEGAL (Note 9)
	L	L	Н	L	BA, A10	PRE/PALL	Pre-charge ^(Note 12)
-	L	L	L	Н	Х	REF/SELF	ILLEGAL (Note 10)
	L	L	L	L	Op-Code	MRS	ILLEGAL
	Н	Х	Х	Х	Х	DESL	Continue burst to end \rightarrow Row active
	L	Н	Н	Н	Х	NOP	Continue burst to end \rightarrow Row active
	L	Н	Н	L	Х	BST	Burst stop \rightarrow Row active
	L	н	L	Н	BA/CA/A10	READ/READA	Terminate burst, new read: Determine AP ^(Note 13)
Read	L	L	L	L	BA/CA/A10	WRIT/WRITA	Terminate burst, start write: Determine AP ^(Note 13, 14)
	L	L	Н	Н	BA/RA	ACT	ILLEGAL ^(Note 9)
	L	L	н	L	BA, A10	PRE/PALL	Terminate burst, pre-charging (Note 10)
-	L	L	L	Н	Х	REF/SELF	ILLEGAL
	L	L	L	L	Op-Code	MRS	ILLEGAL
	Н	Х	Х	Х	х	DESL	Continue burst to end \rightarrow Write recovering
	L	Н	н	Н	Х	NOP	Continue burst to end \rightarrow Write recovering
	L	Н	Н	L	Х	BST	Burst stop \rightarrow Row active
	L	н	L	н	BA/CA/A10	READ/READA	Terminate burst, start read: Determine AP 7, 8 ^(Note 13, 14)
Write	L	L	L	L	BA/CA/A10	WRIT/WRITA	Terminate burst, new write: Determine AP 7 ^(Note 13)
	L	L	Н	н	BA/RA	ACT	ILLEGAL ^(Note 9)
	L	L	н	L	BA, A10	PRE/PALL	Terminate burst, pre-charging (Note 15)
	L	L	L	Н	Х	REF/SELF	ILLEGAL
ŀ					Op-Code	MRS	ILLEGAL

4. Operative Command Table (Note 7)

Remark H = High level, L = Low level, X = High or Low level (Don't care)

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4. Operative Command Table (Continued) (Note 7)

Current State	/CS	/R	/C	/W	Addr.	Command	Action
	Н	х	х	Х	х	DESL	Continue burst to end \rightarrow Pre-charging
	L	н	Н	Н	х	NOP	Continue burst to end \rightarrow Pre-charging
	L	Н	Н	L	Х	BST	ILLEGAL
Read with	L	Н	L	Н	BA/CA/A10	READ/READA	ILLEGAL (Note 9)
AP	L	Н	L	L	BA/CA/A10	WRIT/WRITA	ILLEGAL ^(Note 9)
	L	L	Н	Н	BA/RA	ACT	ILLEGAL ^(Note 9)
	L	L	Н	L	BA, A10	PRE/PALL	ILLEGAL ^(Note 9)
	L	L	L	Н	Х	REF/SELF	ILLEGAL
	L	L	L	L	Op-Code	MRS	ILLEGAL
	Н	х	х	Х	х	DESL	Burst to end \rightarrow Write recovering with auto pre-charge
	L	Н	Н	Н	х	NOP	Continue burst to end \rightarrow Write recovering with auto pre-charge
	L	Н	Н	L	Х	BST	ILLEGAL
Write with	L	Н	L	Н	BA/CA/A10	READ/READA	ILLEGAL (Note 9)
AP	L	Н	Г	L	BA/CA/A10	WRIT/WRITA	ILLEGAL ^(Note 9)
	L	L	Н	Н	BA/RA	ACT	ILLEGAL ^(Note 9)
	L	L	Н	L	BA, A10	PRE/PALL	ILLEGAL ^(Note 9)
	L	L	L	Н	Х	REF/SELF	ILLEGAL
	L	L	L	L	Op-Code	MRS	ILLEGAL
	Н	Х	Х	Х	Х	DESL	Nop \rightarrow Enter idle after t _{RP}
	L	Н	Н	Н	Х	NOP	Nop \rightarrow Enter idle after t _{RP}
	L	Н	Н	L	Х	BST	ILLEGAL
	L	Н	L	Н	BA/CA/A10	READ/READA	ILLEGAL (Note 9)
Pre-charging	L	Н	L	L	BA/CA/A10	WRIT/WRITA	ILLEGAL ^(Note 9)
	L	L	Н	Н	BA/RA	ACT	ILLEGAL ^(Note 9)
	L	L	Н	L	BA, A10	PRE/PALL	Nop \rightarrow Enter idle after t _{RP}
	L	L	L	Н	Х	REF/SELF	ILLEGAL
	L	L	L	L	Op-Code	MRS	ILLEGAL
	Н	Х	Х	Х	Х	DESL	Nop \rightarrow Enter idle after t _{RCD}
	L	Н	Н	Н	Х	NOP	Nop \rightarrow Enter idle after t _{RCD}
	L	Н	Н	L	Х	BST	ILLEGAL
D.	L	Н	L	Н	BA/CA/A10	READ/READA	ILLEGAL (Note 9)
Row Activating	L	Н	L	L	BA/CA/A10	WRIT/WRITA	ILLEGAL (Note 9)
, ion can ig	L	L	Н	Н	BA/RA	ACT	ILLEGAL (Note 9, 16)
	L	L	Н	L	BA, A10	PRE/PALL	ILLEGAL ^(Note 9)
	L	L	L	Н	Х	REF/SELF	ILLEGAL
	L	L	L	L	Op-Code	MRS	ILLEGAL

Remark H = High level, L = Low level, X = High or Low level (Don't care), AP = Auto Pre-charge

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Current State	/CS	/R	/C	/W	Addr.	Command	Action
	Н	Х	Х	Х	Х	DESL	Nop \rightarrow Enter row active after t _{DPL}
	L	Н	Н	Н	Х	NOP	Nop \rightarrow Enter row active after t _{DPL}
	L	Н	Н	L	Х	BST	Nop \rightarrow Enter row active after t _{DPL}
	L	Н	L	Н	BA/CA/A10	READ/READA	Start read, Determine AP
Write Recovering	L	Н	L	L	BA/CA/A10	WRIT/WRITA	New write, Determine AP (Note 14)
Recovering	L	L	Н	н	BA/RA	ACT	ILLEGAL ^(Note 9)
	L	L	Н	L	BA, A10	PRE/PALL	ILLEGAL ^(Note 9)
	L	L	L	Н	Х	REF/SELF	ILLEGAL
	L	L	L	L	Op-Code	MRS	ILLEGAL
	Н	Х	Х	Х	Х	DESL	Nop \rightarrow Enter pre-charge after t _{DPL}
	L	н	Н	Т	Х	NOP	Nop \rightarrow Enter pre-charge after t _{DPL}
	L	Н	Н	L	Х	BST	Nop \rightarrow Enter pre-charge after t _{DPL}
Write	L	Н	L	Н	BA/CA/A10	READ/READA	ILLEGAL ^(Note 9, 14)
Recovering	L	Н	L	L	BA/CA/A10	WRIT/WRITA	ILLEGAL ^(Note 9)
with AP	L	L	Н	Н	BA/RA	ACT	ILLEGAL ^(Note 9)
	L	L	Н	L	BA, A10	PRE/PALL	ILLEGAL
	L	L	L	Н	Х	REF/SELF	ILLEGAL
	L	L	L	L	Op-Code	MRS	ILLEGAL
	Н	Х	Х	Х	Х	DESL	Nop \rightarrow Enter idle after t _{RC}
	L	Н	Н	Х	Х	NOP/BST	Nop \rightarrow Enter idle after t _{RC}
Refreshing	L	Н	L	Х	Х	READ/WRIT	ILLEGAL
	L	L	Н	Х	Х	ACT/PRE/PALL	ILLEGAL
	L	L	L	Х	Х	REF/SELF/MRS	ILLEGAL
	Н	Х	Х	Х	Х	DESL	Nop
Mode	L	Н	Н	Н	Х	NOP	Nop
Register	L	Н	Н	L	Х	BST	ILLEGAL
Accessing	L	Н	L	Х	Х	READ/WRIT	ILLEGAL
	L	L	Х	Х	Х	ACT/PRE/PALL/ REF/SELF/MRS	ILLEGAL

4. Operative Command Table (Continued) (Note 7)

Remark H = High level, L = Low level, X = High or Low level (Don't care), AP = Auto Pre-charge

Note 7: All entries assume that CKE was active (High level) during the preceding clock cycle.

Note 8: If all banks are idle, and CKE is inactive (Low level), SDRAM will enter Power down mode. All input buffers except CKE will be disabled.

Note 9: Illegal to bank in specified states;

Function may be legal in the bank indicated by Bank Address (BA), depending on the state of that bank.

- *Note 10:* If all banks are idle, and CKE is inactive (Low level), SDRAM will enter Self refresh mode. All input buffers except CKE will be disabled.
- **Note 11:** Illegal if t_{RCD} is not satisfied.
- *Note 12:* Illegal if t_{RAS} is not satisfied.
- Note 13: Must satisfy burst interrupt condition.
- Note 14: Must satisfy bus contention, bus turn around, and/or write recovery requirements.
- Note 15: Must mask preceding data which don't satisfy t_{DPL}.
- *Note 16:* Illegal if t_{RRD} is not satisfied.

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Current StateImage: CRL or CRL or Ref/CS/R/C/WAddr.Actionn-1nNXXXXXXAddr.ActionHXXXXXXXXYLHHXXXXXSelf refresh recoveryLHLHHXXSelf refresh recoveryLHLHLXXILLEGALLHLXXXILLEGALLLXXXXMaintain self refreshHHHXXXXIdle after t _{RC}	exit self
Self RefreshIAAAAArefreshLHHXXXXSelf refresh recoveryLHLHHXXSelf refresh recoveryLHLHLXXSelf refresh recoveryLHLLXXILLEGALLHLXXXMaintain self refreshLLXXXXX	exit self
Self RefreshLHLHHXXSelf refresh recoveryLHLHLXXILLEGALLHLLXXXILLEGALLLXXXXMaintain self refresh	
LHLHLXXILLEGALLHLLXXXILLEGALLLXXXXMaintain self refresh	
L H L L X X ILLEGAL L L X X X X Maintain self refresh	
L L X X X X X Maintain self refresh	
H H L H H X X Idle after t _{RC}	
H H L H L X X ILLEGAL	
Self Refresh H H L L X X X ILLEGAL	
Recovery H L H X X X X ILLEGAL	
H L L H H X X ILLEGAL	
H L L H L X X ILLEGAL	
H L L L X X ILLEGAL	
H X X X X X X INVALID, CLK(n-1) would power down	əxit
Power Down L H X X X X X Exit power down \rightarrow Idle	
L L X X X X X Maintain power down mod	е
H H H X X X Defer to exercise in One	rotivo
H H L H X X Command Table	ralive
H H L L H X Refresh	
H H L L L Op-Code	
Both Banks H L H X X X Refer to operations in Ope	rative
Idle H L L H X X Command Table	
H L L L H X Self refresh (Note 17)	
H L L L L Op-Code Refer to operations in Ope	rative
L X X X X X X Power down (Note 17)	
H X X X X X Row Active H X X X X Refer to operations in Operations in Operations in Operations in Operations in Operations in Operations	rative
L X X X X X Power down (Note 17)	
H H X X X X Command Table	rative
Any State Other than Listed aboveHLXXXXXBegin clock suspend next (Note 18)	cycle
L H X X X X X Exit clock suspend next cy	cle
L L X X X X X Maintain clock suspend	-

5. Command Truth Table for CKE

Remark: H = High level, L = Low level, X = High or Low level (Don't care)

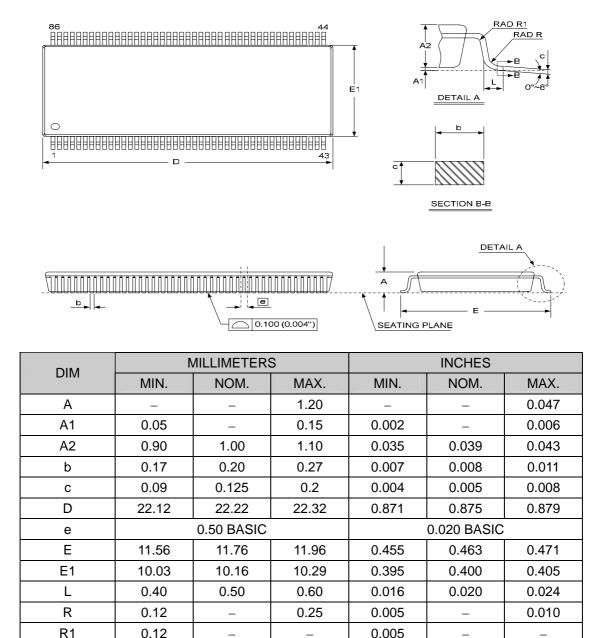
Notes 17: Self refresh can be entered only from the both banks idle state.

Power down can be entered only from both banks idle or row active state.

Notes 18: Must be legal command as defined in Operative Command Table

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Package Description



* Controlling dimension: millimeters

* Dimension D does not include mold protrusion. Mold protrusion shall not exceed 0.15mm (0.006") per side. Dimension E1 does not include interlead protrusion. Interlead protrusion shall not exceed 0.25mm (0.01") per side.

* Dimension b does not include dambar protrusions/intrusion. Allowable dambar protrusion shall not cause the lead to be wider than the MAX b dimension by more than 0.13mm. Dambar intrusion shall not cause the lead to be narrower than the MIN b dimension by more than 0.07mm.